(19) World Intellectual Property Organization International Bureau





(43) International Publication Date 27 March 2003 (27.03.2003)

PCT

(10) International Publication Number WO 03/025998 A3

(51) International Patent Classification7: H01L 21/60, 23/485

(21) International Application Number: PCT/US02/26607

(22) International Filing Date: 20 August 2002 (20.08.2002)

(25) Filing Language: English

(26) Publication Language: English

(30) Priority Data: 09/952,527 14 September 2001 (14.09.2001)

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(81) Designated States (national): AE, AG, AL, AM, AT, AU, AZ, BA, BB, BG, BR, BY, BZ, CA, CH, CN, CO, CR, CU, CZ, DE, DK, DM, DZ, EC, EE, ES, FI, GB, GD, GE, GH, GM, HR, HU, ID, IL, IN, IS, JP, KE, KG, KP, KR, KZ, LC, LK, LR, LS, LT, LU, LV, MA, MD, MG, MK, MN, MW, MX, MZ, NO, NZ, OM, PH, PL, PT, RO, RU, SD, SE, SG, SI, SK, SL, TJ, TM, TN, TR, TT, TZ, UA, UG, UZ, VC, VN, YU, ZA, ZM, ZW.

(84) Designated States (regional): ARIPO patent (GH, GM, KE, LS, MW, MZ, SD, SL, SZ, TZ, UG, ZM, ZW), Eurasian patent (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM), European patent (AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, IE, IT, LU, MC, NL, PT, SE, SK, TR), OAPI patent (BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, ML, MR, NE, SN, TD, TG).

Published:

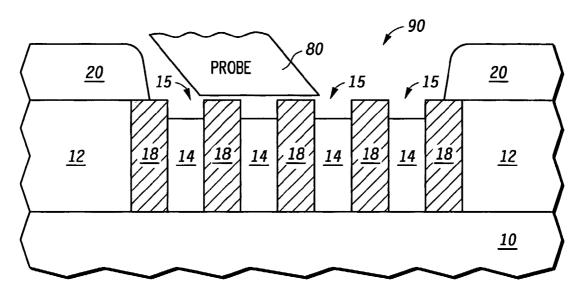
with international search report

(88) Date of publication of the international search report:

12 June 2003

For two-letter codes and other abbreviations, refer to the "Guidance Notes on Codes and Abbreviations" appearing at the beginning of each regular issue of the PCT Gazette.

(54) Title: METHOD OF FORMING A BOND PAD AND STRUCTURE THEREOF



(57) Abstract: A bond pad (100) is formed by first providing a planarized combination of copper (18) and silicon oxide features (14) in a bond pad region. The silicon oxide features (14) are etched back to provide a plurality recesses (15) in the copper in the bond pad region. A corrosion barrier (22) is formed over the copper and the silicon oxide features in the recesses. Probing of the wafer (10) is done by directly applying the probe to the copper. A wire bond (24) is directly attached to the copper (18). The probe (80) is prevented from penetrating all the way through the copper (18) because the recessed features (15) are present. With the recesses (15) in the copper, the wire bond (24) more readily breaks down and penetrates the corrosion barrier and is also less likely to slip on the bond pad (100).

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INTERNATIONAL SEARCH REPORT

Internati Application No PCT/US 02/26607

A. CLASSIFICATION OF SUBJECT MATTER IPC 7 H01L21/60 H01L23/485

According to International Patent Classification (IPC) or to both national classification and IPC

B. FIELDS SEARCHED

Documentation searched other than minimum documentation to the extent that such documents are included in the fields searched

Electronic data base consulted during the international search (name of data base and, where practical, search terms used)

EPO-Internal, WPI Data, PAJ, IBM-TDB, INSPEC

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X	PATENT ABSTRACTS OF JAPAN vol. 1995, no. 02, 31 March 1995 (1995-03-31) & JP 06 318590 A (NEC CORP), 15 November 1994 (1994-11-15)	4-6,8	
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Further documents are listed in the continuation of box C.	Patent family members are listed in annex.		
Special categories of cited documents: A* document defining the general state of the art which is not considered to be of particular relevance E* earlier document but published on or after the international filling date L* document which may throw doubts on priority claim(s) or which is cited to establish the publication date of another citation or other special reason (as specified) O* document referring to an oral disclosure, use, exhibition or other means P* document published prior to the international filling date but later than the priority date claimed	 "T" later document published after the international filing date or priority date and not in conflict with the application but cited to understand the principle or theory underlying the invention "X" document of particular relevance; the claimed invention cannot be considered novel or cannot be considered to involve an inventive step when the document is taken alone "Y" document of particular relevance; the claimed invention cannot be considered to involve an inventive step when the document is combined with one or more other such documents, such combination being obvious to a person skilled in the art. "&" document member of the same patent family 		
Date of the actual completion of the international search 12 March 2003	Date of mailing of the international search report 19/03/2003		
Name and mailing address of the ISA European Patent Office, P.B. 5818 Patentlaan 2 NL – 2280 HV Rijswijk Tel. (+31-70) 340-2040, Tx. 31 651 epo nl, Fax: (+31-70) 340-3016	Authorized officer Ploner, G		

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